2309409-2 <

DDR4 DIMM

TE Internal #: 2309409-2 SO DIMM Sockets, Small Outline (SO), Stack Height .205 in [5.2 mm], Right Angle Module Orientation, Surface Mount Mount, Cable-to-Board, DDR4 DIMM

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DRAM Type: Small Outline (SO) Stack Height: 5.2 mm [.205 in] Module Orientation: Right Angle PCB Mounting Style: Surface Mount Connector System: Cable-to-Board

All DDR4 SO DIMM SOCKETS (39)

Features

Product Type Features

Center Post

Without

| DRAM Type | Small Outline (SO) |
|-----------------------------------|-----------------------|
| Connector System | Cable-to-Board |
| Sealable | No |
| Connector & Contact Terminates To | Printed Circuit Board |
| Product Type | Socket |
| Configuration Features | |
| Center Key | Offset Left |
| Number of Keys | 1 |
| Module Orientation | Right Angle |
| Number of Positions | 260 |
| Number of Rows | 2 |
| Keying | Standard |
| Electrical Characteristics | |
| DRAM Voltage | 1.2 V |
| Signal Characteristics | |

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| SGRAM Voltage | 1.2 V |
|--|--------------------------------|
| Body Features | |
| Ejector Location | Both Ends |
| Latch Material | High Temperature Thermoplastic |
| Retention Post Location | Both Ends |
| Module Key Type | Offset Left |
| Ejector Type | Locking |
| Connector Profile | Low |
| Contact Features | |
| Socket Style | SO DIMM |
| PCB Contact Termination Area Plating Material | Gold Flash |
| Contact Base Material | Copper Alloy |
| Contact Mating Area Plating Material | Gold |
| Contact Mating Area Plating Material Thickness | .127 μm[5 μin] |
| Contact Current Rating (Max) | .5 A |
| Socket Type | Memory Card |
| | |

Termination Features

| Insertion Style | Cam-In |
|-----------------------------|--------------------------------|
| Mechanical Attachment | |
| PCB Mount Retention | With |
| PCB Mount Retention Type | Solder Peg |
| PCB Mounting Style | Surface Mount |
| Connector Mounting Type | Board Mount |
| Housing Features | |
| Centerline (Pitch) | .5 mm[.02 in] |
| Housing Color | Black |
| Housing Material | High Temperature Thermoplastic |
| Dimensions | |
| Stack Height | 5.2 mm[.205 in] |
| Row-to-Row Spacing | 8.2 mm[.322 in] |
| Usage Conditions | |
| Operating Temperature Range | -55 – 85 °C[-67 – 185 °F] |

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Operation/Application

| Circuit Application | Power |
|---|---|
| Industry Standards | |
| UL Flammability Rating | UL 94V-0 |
| Packaging Features | |
| Packaging Method | Tape & Reel |
| Packaging Quantity | 800 |
| Product Compliance For compliance documentation, visit the product page on TE.com> EU RoHS Directive 2011/65/EU | Compliant |
| EU ELV Directive 2000/53/EC | Compliant |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold |
| EU REACH Regulation (EC) No. 1907/2006 | Current ECHA Candidate List: JUNE 2022 |

Halogen Content

Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free

Solder Process Capability

Reflow solder capable to 260°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts

SO DIMM Sockets, Small Outline (SO), Stack Height .205 in [5.2 mm], Right Angle Module Orientation, Surface Mount Mount, Cable-to-Board, DDR4 DIMM

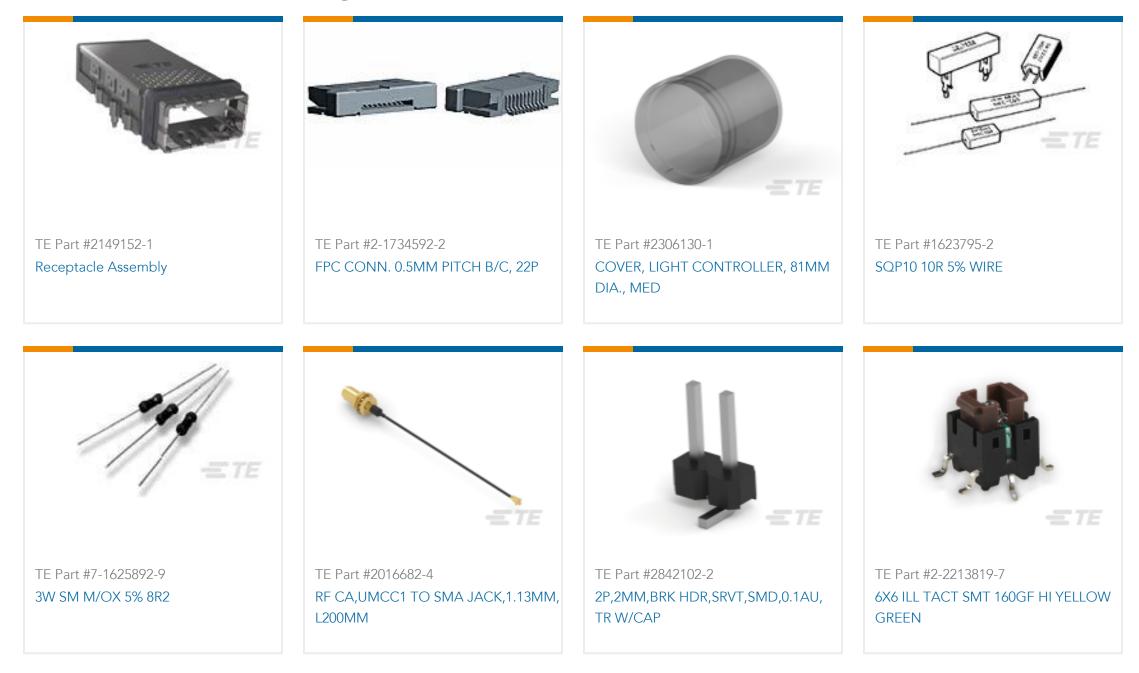




Also in the Series DDR4 DIMM



Customers Also Bought





SO DIMM Sockets, Small Outline (SO), Stack Height .205 in [5.2 mm], Right Angle Module Orientation, Surface Mount Mount, Cable-to-Board, DDR4 DIMM



Documents

Product Drawings DDR4 SODIMM 260P 5.2H STD

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_2309409-2_1.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_2309409-2_1.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_2309409-2_1.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Product Specifications Application Specification

English

Product Environmental Compliance

Product Compliance

English

Product Compliance

English